

# ON Semiconductor

## Is Now

The logo for onsemi, featuring the word "onsemi" in a dark teal, lowercase, sans-serif font. The letter "i" is stylized with a white dot and a teal vertical bar. A small orange triangle is positioned above the top right of the "i". A trademark symbol (TM) is located to the right of the logo.

To learn more about onsemi™, please visit our website at  
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# MOSFET – Power, N-Channel, SUPERFET® III, FAST

**650 V, 125 mΩ, 24 A**

## NTHL125N65S3H

### Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET FAST series helps minimize various power systems and improve system efficiency.

### Features

- 700 V @  $T_J = 150^\circ\text{C}$
- Typ.  $R_{DS(on)} = 108\text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 44\text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 379\text{ pF}$ )
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

### Applications

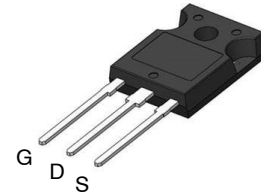
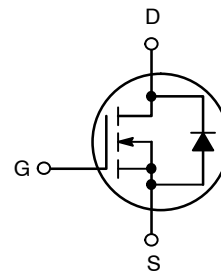
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar



**ON Semiconductor®**

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| $V_{DSS}$ | $R_{DS(ON)}\text{ MAX}$ | $I_D\text{ MAX}$ |
|-----------|-------------------------|------------------|
| 650 V     | 125 mΩ @ 10 V           | 24 A             |



**TO-247 Long Leads  
CASE 340CX**

### MARKING DIAGRAM



T125N65S3H = Specific Device Code  
 A = Assembly Plant Code  
 YWW = Data Code (Year & Week)  
 ZZ = Lot

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# NTHL125N65S3H

## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise noted)

| Symbol                            | Parameter  | Value                                 | Unit |
|-----------------------------------|--|---------------------------------------|------|
| V <sub>DSS</sub>                  | Drain to Source Voltage  | 650                                   | V    |
| V <sub>GSS</sub>                  | Gate to Source Voltage   | - DC                                  | ±30  |
|                                   |  | - AC (f > 1 Hz)                       | ±30  |
| I <sub>D</sub>                    | Drain Current  | - Continuous (T <sub>C</sub> = 25°C)  | 24   |
|                                   |  | - Continuous (T <sub>C</sub> = 100°C) | 15   |
| I <sub>DM</sub>                   | Drain Current  | - Pulsed (Note 1)                     | 67   |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy (Note 2)                              | 216                                   | mJ   |
| I <sub>AS</sub>                   | Avalanche Current (Note 2)   | 4.7                                   | A    |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy (Note 1)                                 | 1.71                                  | mJ   |
| dv/dt                             | MOSFET dv/dt   | 120                                   | V/ns |
|                                   | Peak Diode Recovery dv/dt (Note 3)                                   | 20                                    |      |
| P <sub>D</sub>                    | Power Dissipation  | (T <sub>C</sub> = 25°C)               | 171  |
|                                   |  | - Derate Above 25°C                   | 1.37 |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range                              | -55 to +150                           | °C   |
| T <sub>L</sub>                    | Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds | 260                                   | °C   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I<sub>AS</sub> = 4.7 A, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub> ≤ 12 A, di/dt ≤ 200 A/μs, V<sub>DD</sub> ≤ 400 V, starting T<sub>J</sub> = 25°C.

## THERMAL CHARACTERISTICS

| Symbol           | Parameter                                     | Value | Unit |
|------------------|---|-------|------|
| R <sub>θJC</sub> | Thermal Resistance, Junction to Case, Max.    | 0.73  | °C/W |
| R <sub>θJA</sub> | Thermal Resistance, Junction to Ambient, Max. | 40    |      |

## PACKAGE MARKING AND ORDERING INFORMATION

| Part Number   | Top Marking | Package | Packing Method | Reel Size | Tape Width | Quantity |
|---------------|-------------|---------|----------------|-----------|------------|----------|
| NTHL125N65S3H | T125N65S3H  | TO-247  | Tube           | N/A       | N/A        | 30 Units |

# NTHL125N65S3H

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--------|-----------|-----------------|-----|-----|-----|------|
|--------|-----------|-----------------|-----|-----|-----|------|

### OFF CHARACTERISTICS

|                                     |   |  |     |      |      |      |
|-------------------------------------|---|--|-----|------|------|------|
| BV <sub>DSS</sub>                   | Drain to Source Breakdown Voltage         | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C  | 650 | –    | –    | V    |
|                                     |   | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C | 700 | –    | –    | V    |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Breakdown Voltage Temperature Coefficient | I <sub>D</sub> = 10 mA, Referenced to 25°C                           | –   | 0.63 | –    | V/°C |
| I <sub>DSS</sub>                    | Zero Gate Voltage Drain Current           | V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V                       | –   | –    | 1    | μA   |
|                                     |   | V <sub>DS</sub> = 520 V, T <sub>C</sub> = 125°C                      | –   | 1.3  | –    |      |
| I <sub>GSS</sub>                    | Gate to Body Leakage Current              | V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V                       | –   | –    | ±100 | nA   |

### ON CHARACTERISTICS

|                     |                                      |   |     |     |     |    |
|---------------------|--------------------------------------|---|-----|-----|-----|----|
| V <sub>GS(th)</sub> | Gate Threshold Voltage               | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 2.1 mA | 2.4 | –   | 4.0 | V  |
| R <sub>DS(on)</sub> | Static Drain to Source On Resistance | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A               | –   | 108 | 125 | mΩ |
| g <sub>FS</sub>     | Forward Transconductance             | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 12 A               | –   | 26  | –   | S  |

### DYNAMIC CHARACTERISTICS

|                        |                                   |  |   |      |   |    |
|------------------------|-----------------------------------|--|---|------|---|----|
| C <sub>iss</sub>       | Input Capacitance                 | V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 250 kHz                        | – | 2200 | – | pF |
| C <sub>oss</sub>       | Output Capacitance                |  | – | 34   | – | pF |
| C <sub>oss(eff.)</sub> | Effective Output Capacitance      | V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V                              | – | 379  | – | pF |
| C <sub>oss(er.)</sub>  | Energy Related Output Capacitance | V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V                              | – | 56   | – | pF |
| Q <sub>g(tot)</sub>    | Total Gate Charge at 10V          | V <sub>DS</sub> = 400 V, I <sub>D</sub> = 12 A, V <sub>GS</sub> = 10 V<br>(Note 4) | – | 44   | – | nC |
| Q <sub>gs</sub>        | Gate to Source Gate Charge        |  | – | 11   | – | nC |
| Q <sub>gd</sub>        | Gate to Drain "Miller" Charge     |  | – | 12   | – | nC |
| ESR                    | Equivalent Series Resistance      | f = 1 MHz  | – | 1.1  | – | Ω  |

### SWITCHING CHARACTERISTICS

|                     |                     |   |   |     |   |    |
|---------------------|---------------------|---|---|-----|---|----|
| t <sub>d(on)</sub>  | Turn-On Delay Time  | V <sub>DD</sub> = 400 V, I <sub>D</sub> = 12 A,<br>V <sub>GS</sub> = 10 V, R <sub>g</sub> = 7.5 Ω<br>(Note 4) | – | 22  | – | ns |
| t <sub>r</sub>      | Turn-On Rise Time   |   | – | 9.2 | – | ns |
| t <sub>d(off)</sub> | Turn-Off Delay Time |   | – | 66  | – | ns |
| t <sub>f</sub>      | Turn-Off Fall Time  |   | – | 2.3 | – | ns |

### SOURCE-DRAIN DIODE CHARACTERISTICS

|                 |  |  |   |     |     |    |
|-----------------|--|--|---|-----|-----|----|
| I <sub>S</sub>  | Maximum Continuous Source to Drain Diode Forward Current | –  | – | 24  | A   |    |
| I <sub>SM</sub> | Maximum Pulsed Source to Drain Diode Forward Current     | –  | – | 67  | A   |    |
| V <sub>SD</sub> | Source to Drain Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 12 A                                      | – | –   | 1.2 | V  |
| t <sub>rr</sub> | Reverse Recovery Time                                    | V <sub>DD</sub> = 400 V, I <sub>SD</sub> = 12 A,<br>dI <sub>F</sub> /dt = 100 A/μs | – | 314 | –   | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge                                  |  | – | 4.5 | –   | μC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

# NTHL125N65S3H

## TYPICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

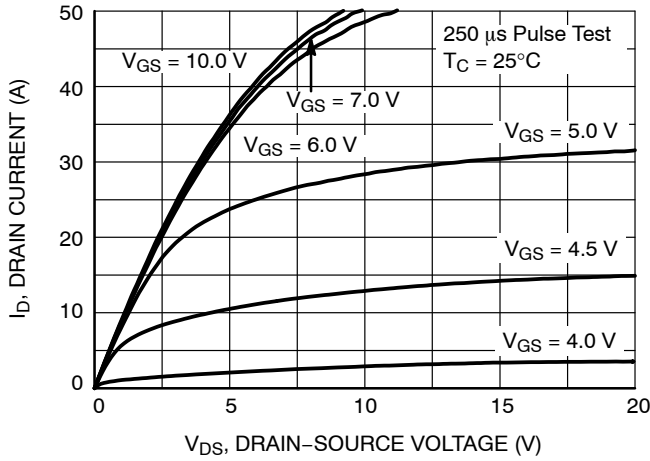


Figure 1. On-Region Characteristics

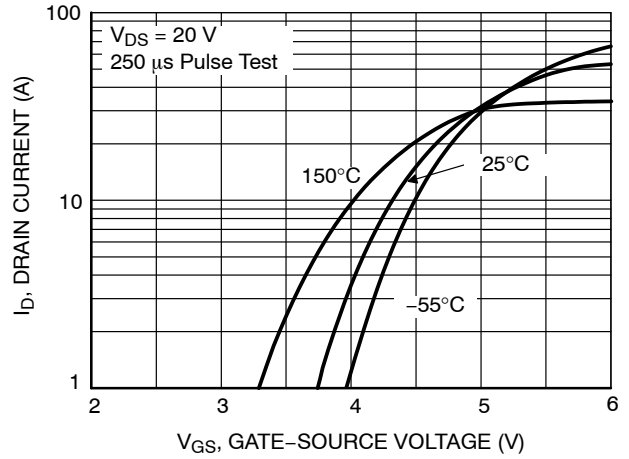


Figure 2. Transfer Characteristics

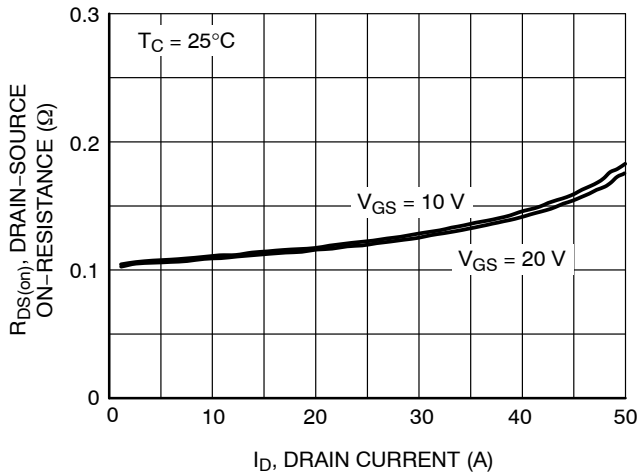


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

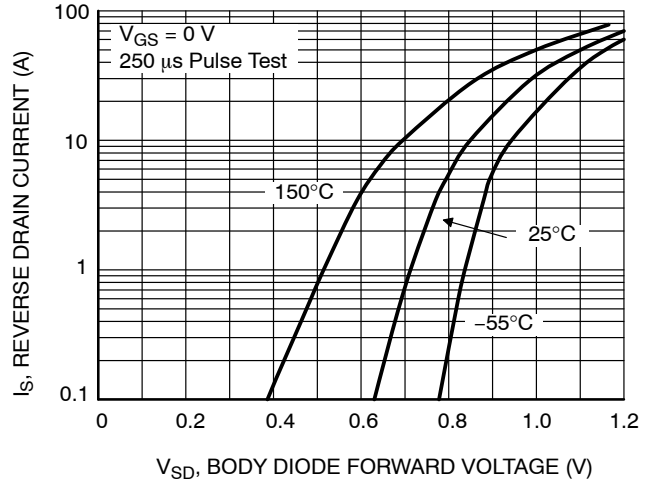


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

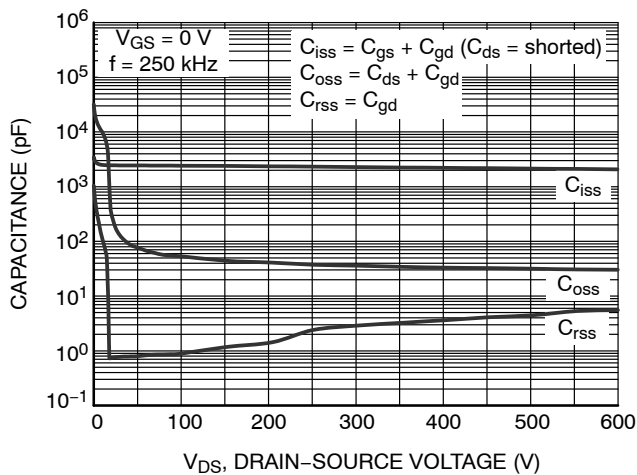


Figure 5. Capacitance Characteristics

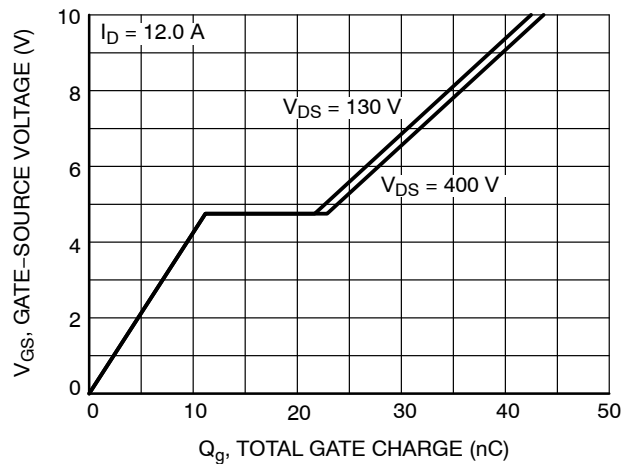
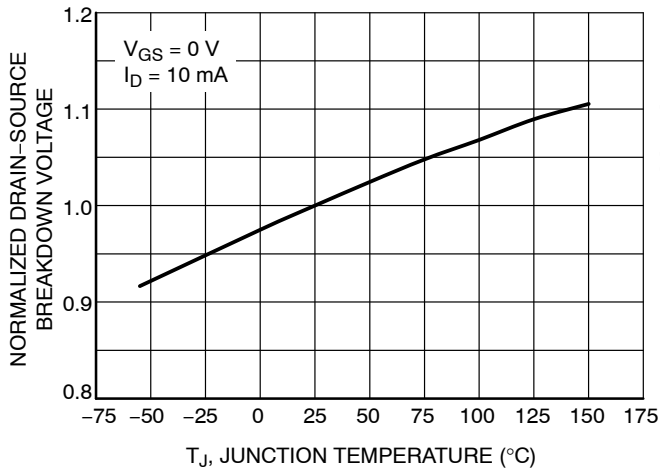


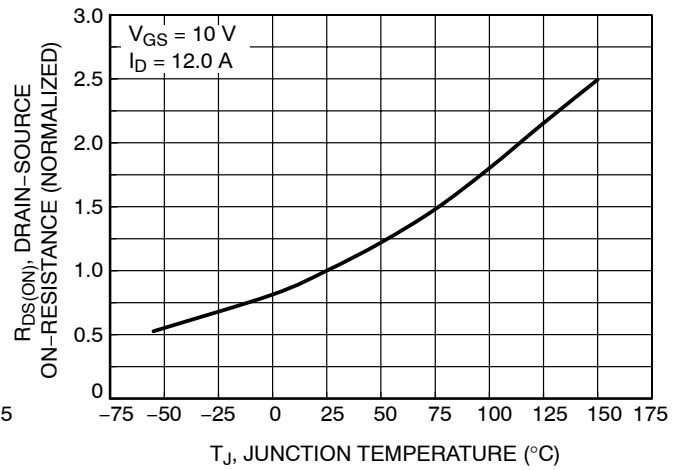
Figure 6. Gate Charge Characteristics

# NTHL125N65S3H

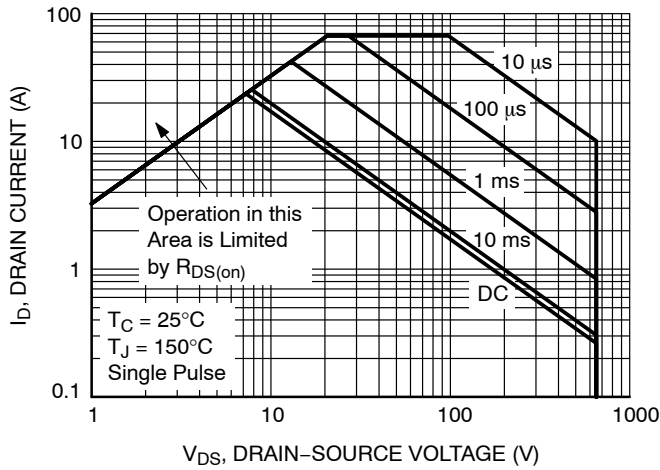
## TYPICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)



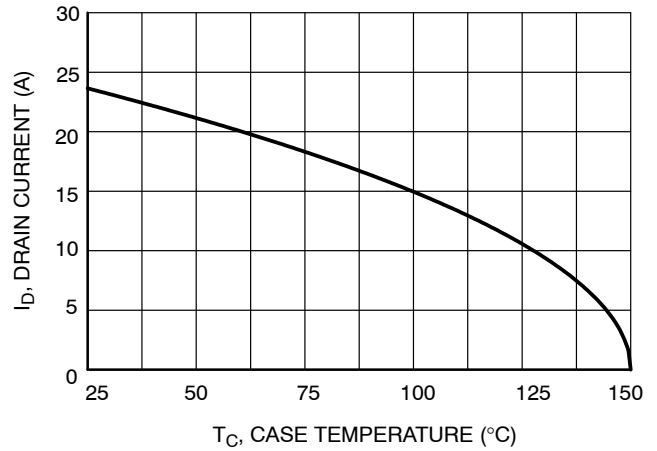
**Figure 7. Breakdown Voltage Variation vs. Temperature**



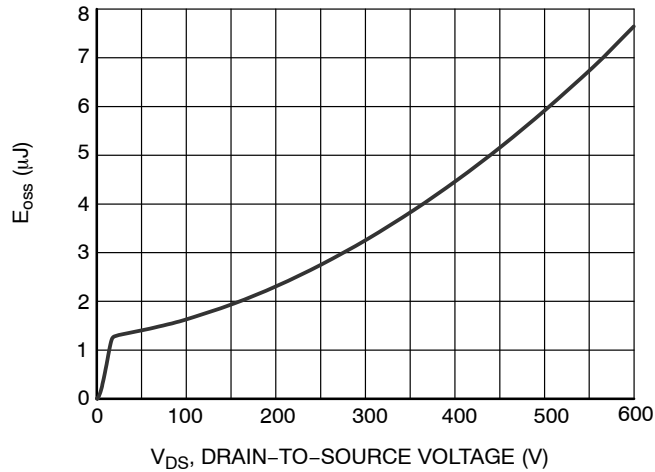
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11.  $E_{OSS}$  vs. Drain to Source Voltage**

# NTHL125N65S3H

## TYPICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted) (continued)

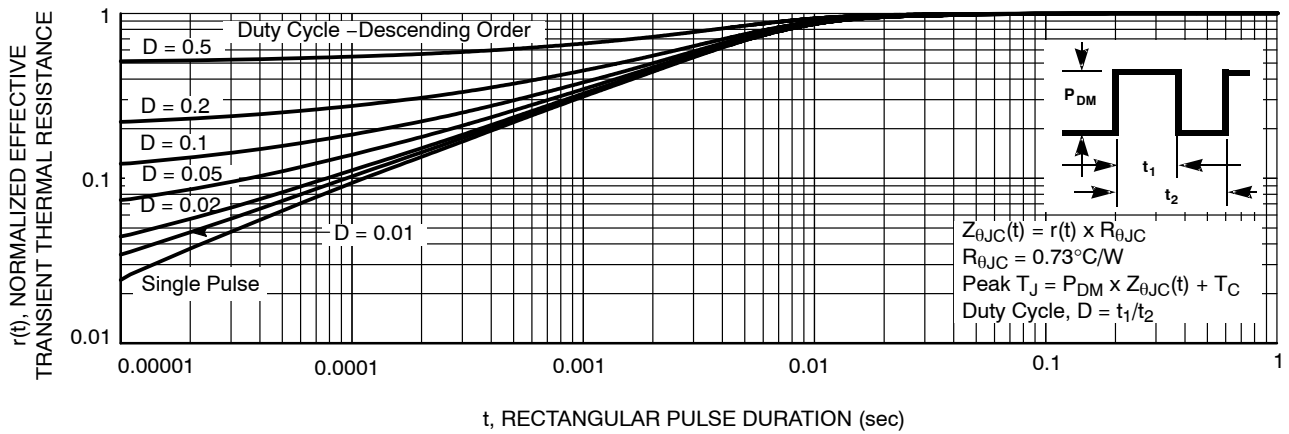


Figure 12. Transient Thermal Response Curve

# NTHL125N65S3H

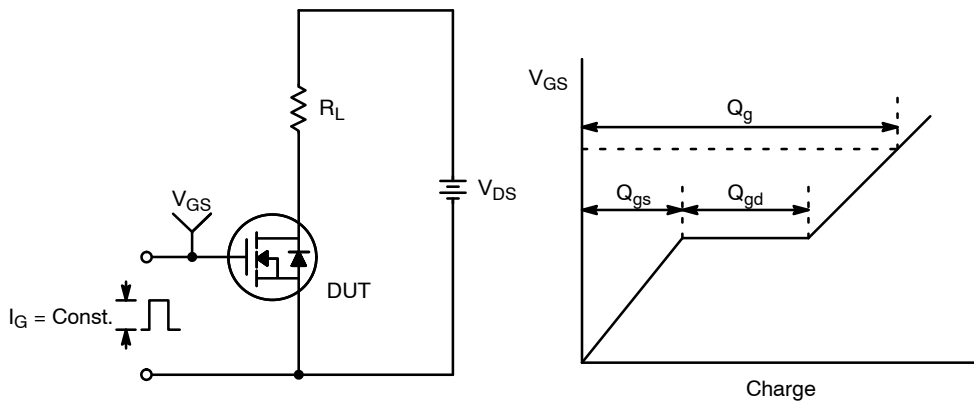


Figure 13. Gate Charge Test Circuit & Waveform

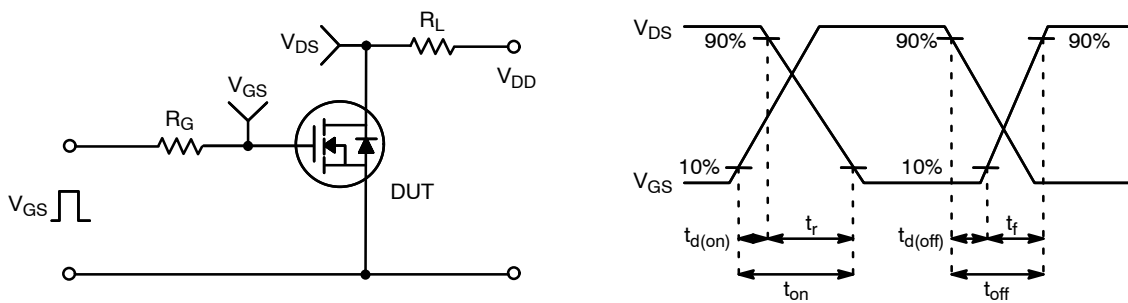


Figure 14. Resistive Switching Test Circuit & Waveforms

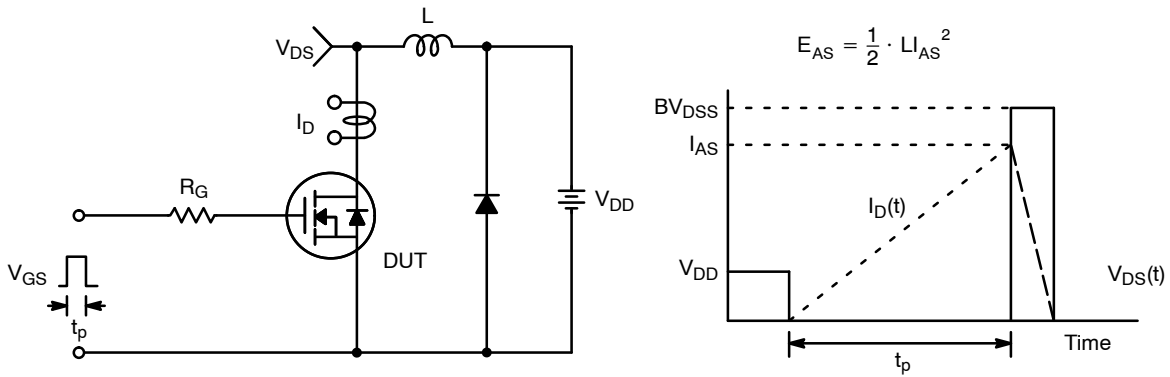
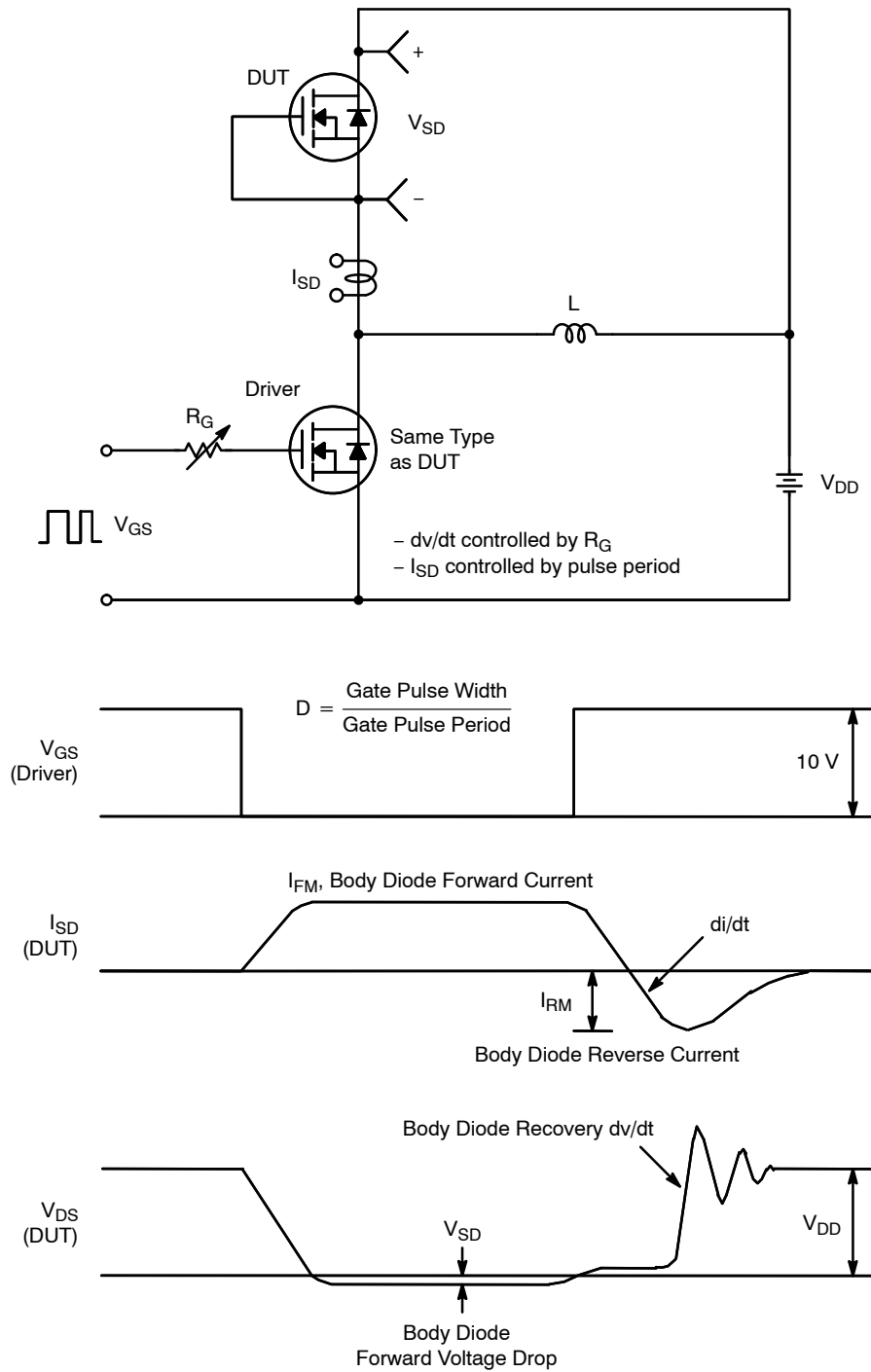


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



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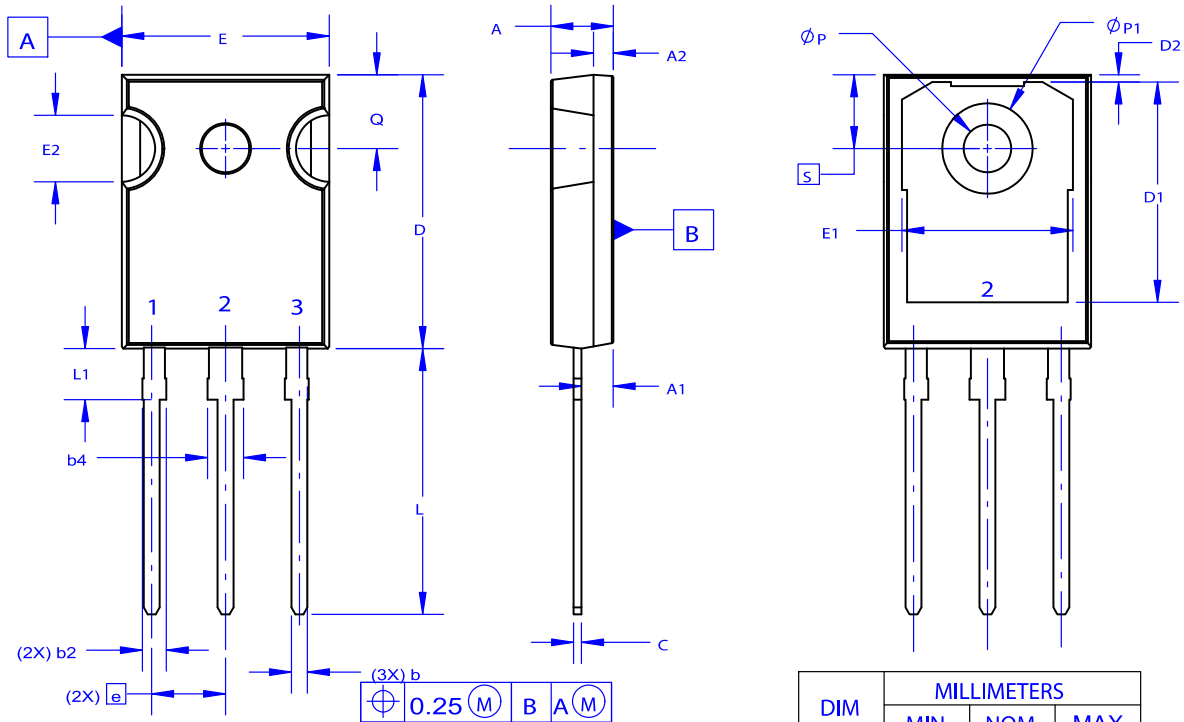


**Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms**

# NTHL125N65S3H

## PACKAGE DIMENSIONS


TO-247-3LD  
CASE 340CX  
ISSUE A



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
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